



## HG-SCN-2-15+

1100-1450MHz 50Ω 2 Way Power Divider  
(频率范围1100-1450MHz, 50Ω 阻抗, 2路功率分配器)

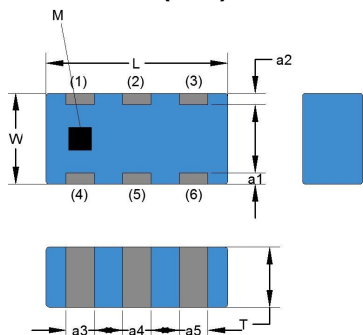
## APPLICATIONS(应用)

- Ideally suitable for CATV applications.(有线电视)

## FEATURES (特点)

- Surface mount (SMT表面贴装)
- 2 Way 0 degree (2路0°)
- 260°C reflow compatible (适用于260°C回流焊)
- RoHS compliant and Pb free (符合RoHS标准, 无铅)
- Available on tape and reel (可用于磁带和卷轴)

## DIMENSIONS(尺寸)

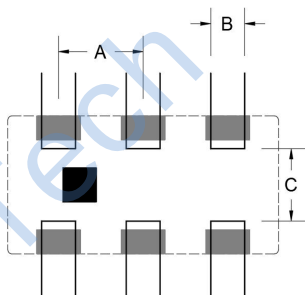


| L     | W        | T      |
|-------|----------|--------|
| 3.2   | 1.6      | 1.5Max |
| a1/a2 | a3/a4/a5 |        |
| 0.28  | 0.52     |        |

Unless otherwise stated dimensions are in mm Tolerance: .xx ±0.2 .xxx ±0.15

除非另有说明, 否则尺寸单位为毫米公差: .xx±0.2.xxx±0.15

## PCB LAYOUT (建议焊盘位置、尺寸)



| A | B   | C    |
|---|-----|------|
| 1 | 0.4 | 0.94 |
|   |     |      |
|   |     |      |

## ELECTRICAL SPECIFICATIONS@25°C:

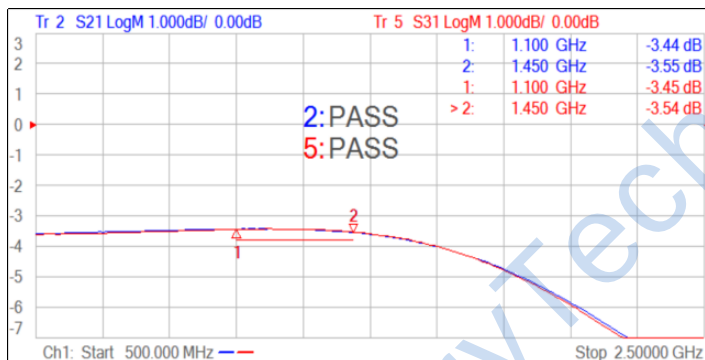
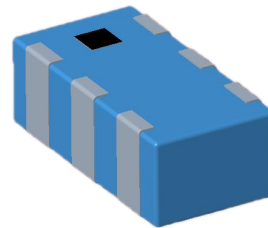
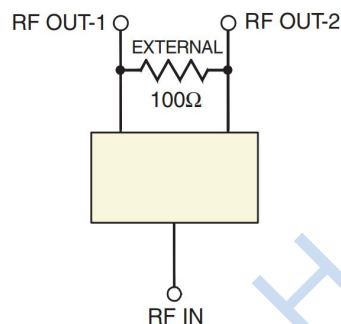
(25°C 室温下相关测试参数)

| Frequency Range (频率范围)    | 1100~1450MHz         | Phase balance (相位平衡度) | ≤3° 1.1~1.45GHz~     |
|---------------------------|----------------------|-----------------------|----------------------|
| Insert loss above 3dB~    | ≤0.8dB~ 1.1~1.45GHz~ | VSWR ( )              | ≤1.5:1~ 1.1~1.45GHz~ |
| Isolation~                | ≥14dB~ 1.1~1.45GHz~  | Return Loss~          | ≥14dB~ 1.1~1.45GHz~  |
| Amplitude balance (幅度平衡度) | ≤0.4dB~ 1.1~1.45GHz~ |                       |                      |

## TEST CURVE (测试曲线)

## 1.Total insertion loss (总插入损耗)

(insertion loss+3dB allocation loss) (插入损耗+3dB分配损耗)

Product Appearance Diagram  
(产品示意图)FUNCTIONAL SCHEMATIC  
(产品原理图)PIN CONFIGURATION  
(引脚配置)

| Pin No. | Function |
|---------|----------|
| 1       | GND      |
| 2       | Input    |
| 3       | GND      |
| 4       | Output 1 |
| 5       | GND      |
| 6       | Output 2 |

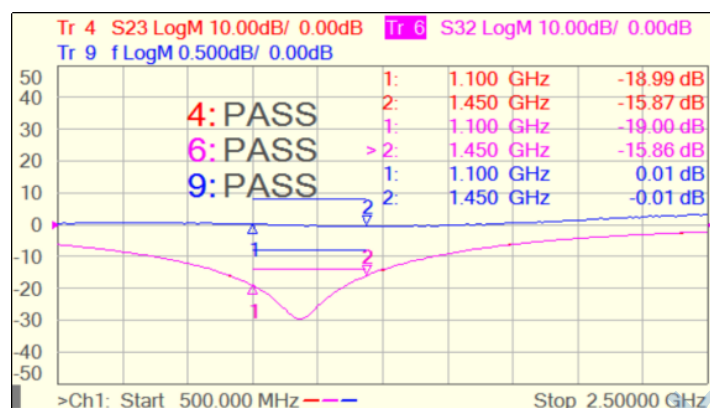
ABSOLUTE MAXIMUM RATINGS  
(参数配置)

| Parameter                                         | Value       |
|---------------------------------------------------|-------------|
| Input RF Power (输入功率)                             | 20W Max     |
| Chips Operating & Storage Temperature (芯片工作/存储温度) | -55 to 85 ℃ |
| Storage temperature after packaging (包装后存储温度)     | -10 to 40 ℃ |
| Storage humidity after packaging(包装后相对湿度)         | ≤70%        |

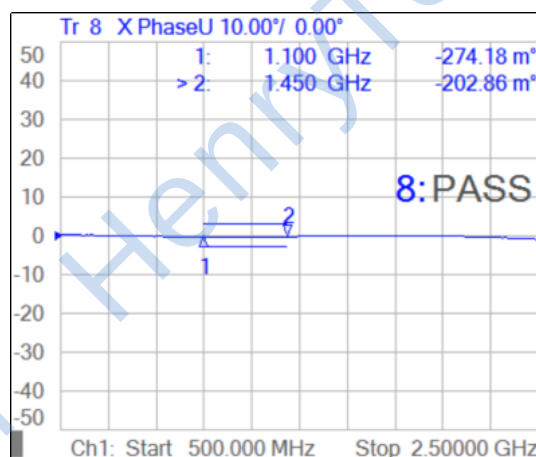


## TEST CURVE

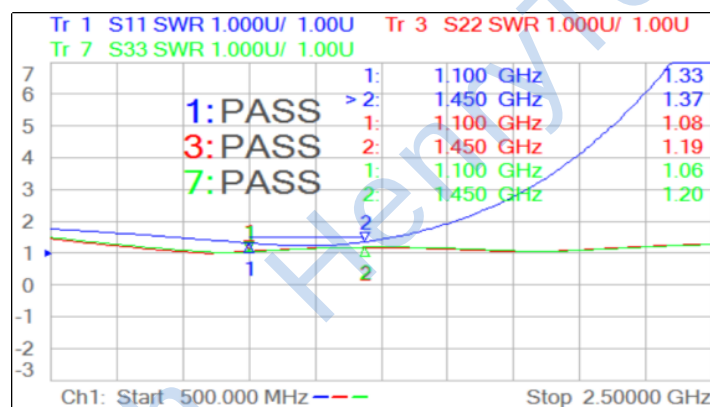
### 2.Isolation And Amplitude Balance



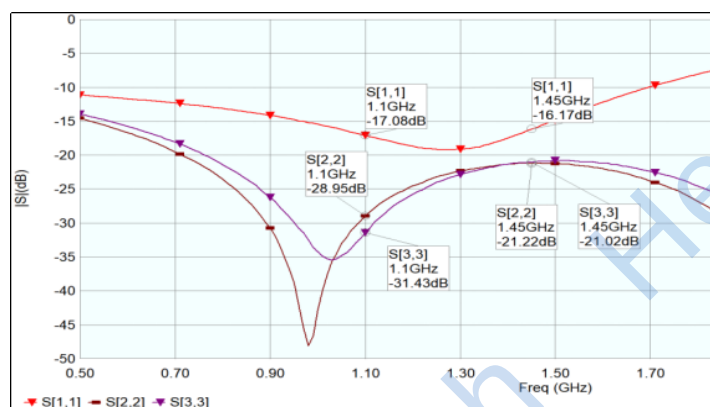
### 3.Phase Balance



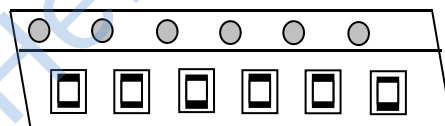
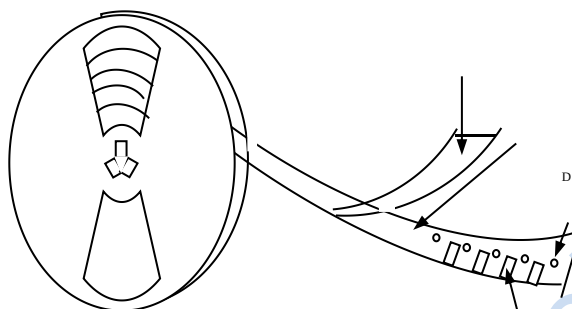
### 4.VSWR



### 5.Return Loss

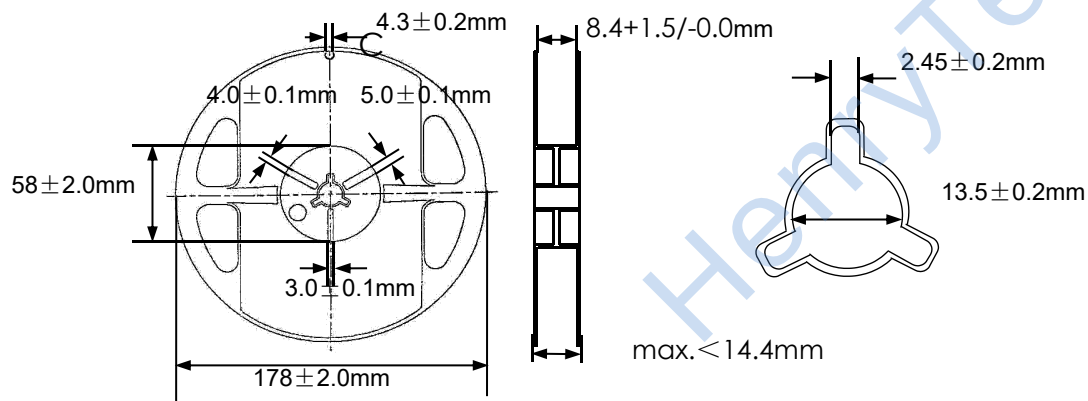


## Packaging method (包装方式)



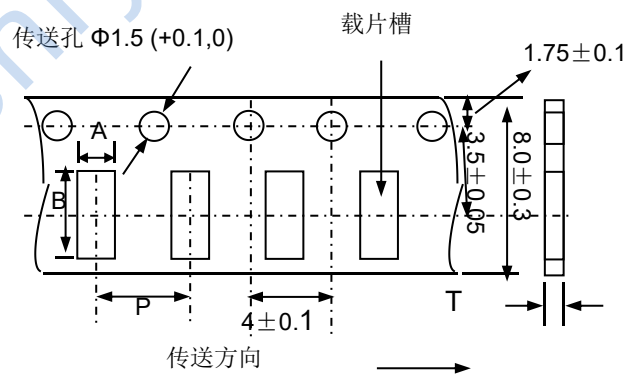
说明：当编带按本图所示由上往下的方向拉出编带时，传送孔位于编带的右侧。

Tape size (卷带尺寸)



Carrier size (载带尺寸)

塑带



| Type | A       | B       | P       | Tmax. |
|------|---------|---------|---------|-------|
| 3216 | 1.8±0.1 | 3.4±0.1 | 4.0±0.1 | 1.5   |